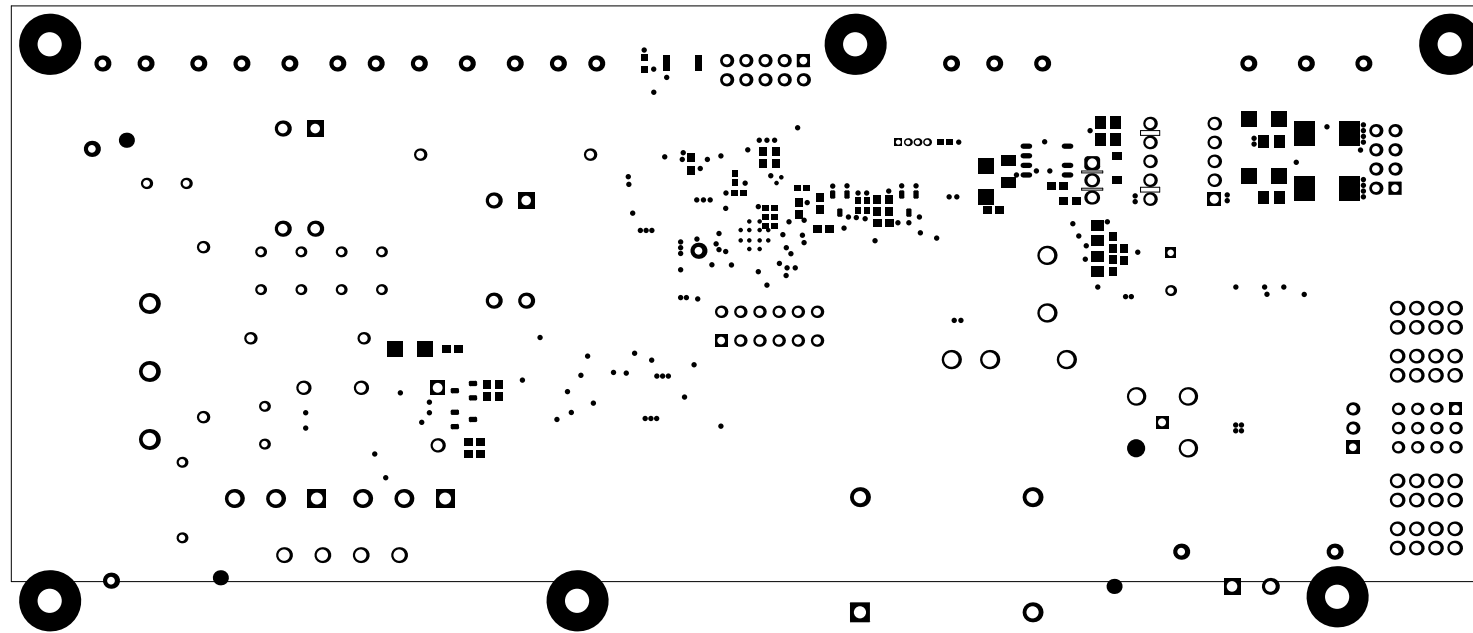
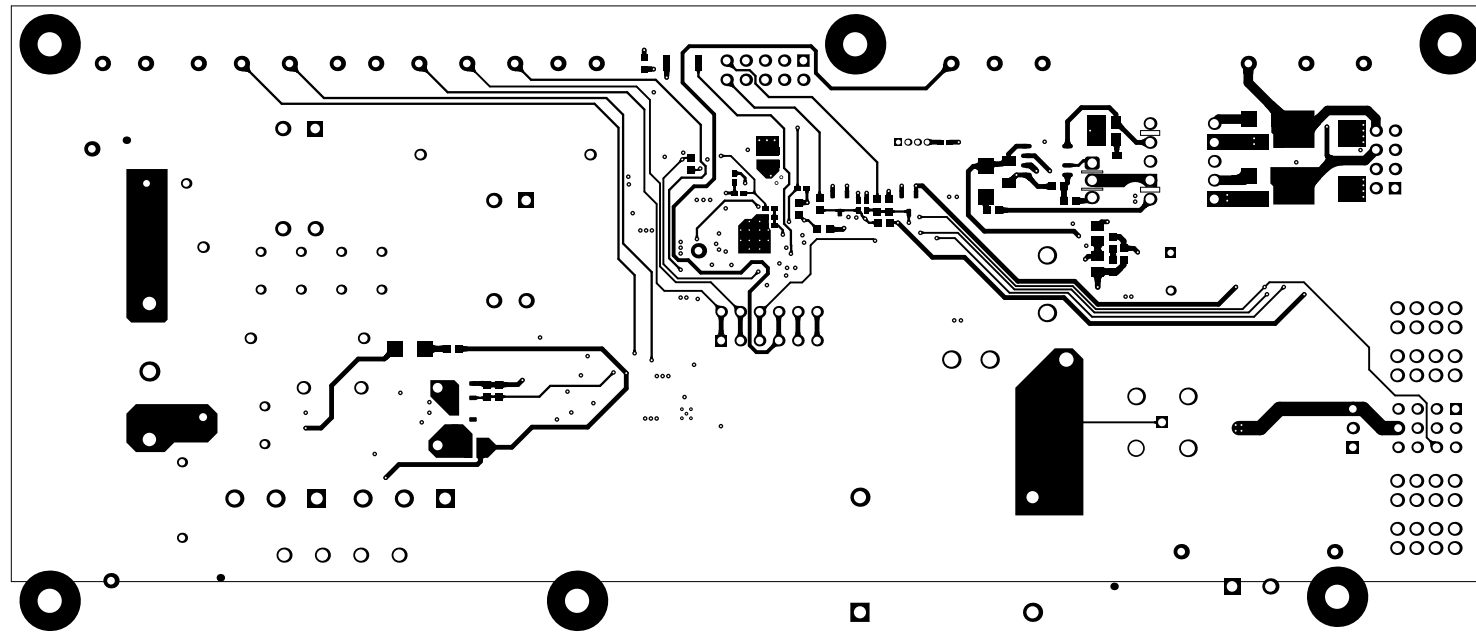


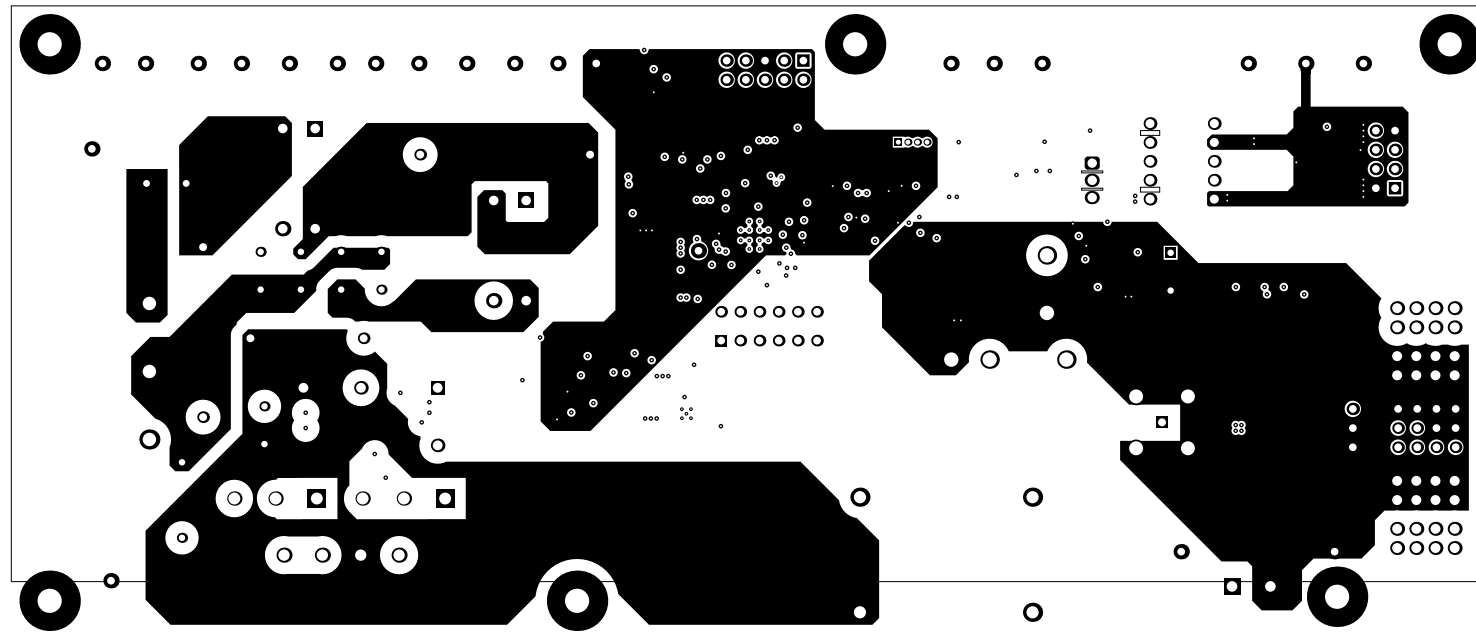
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20873	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Top Overlay	GENERATED : 6/6/2017	1:50:56 PM	TEXAS INSTRUMENTS



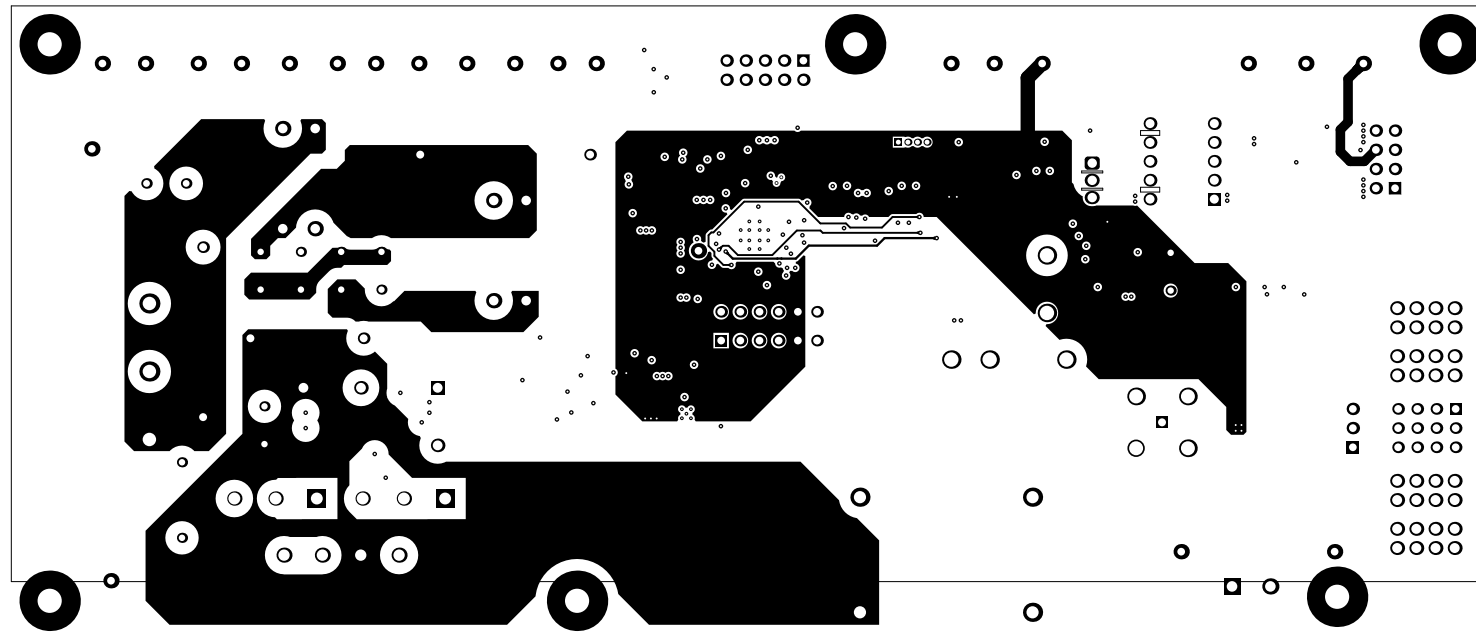
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20873	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Top Solder Mask	GENERATED : 6/6/2017 1:50:58 PM	TEXAS INSTRUMENTS	



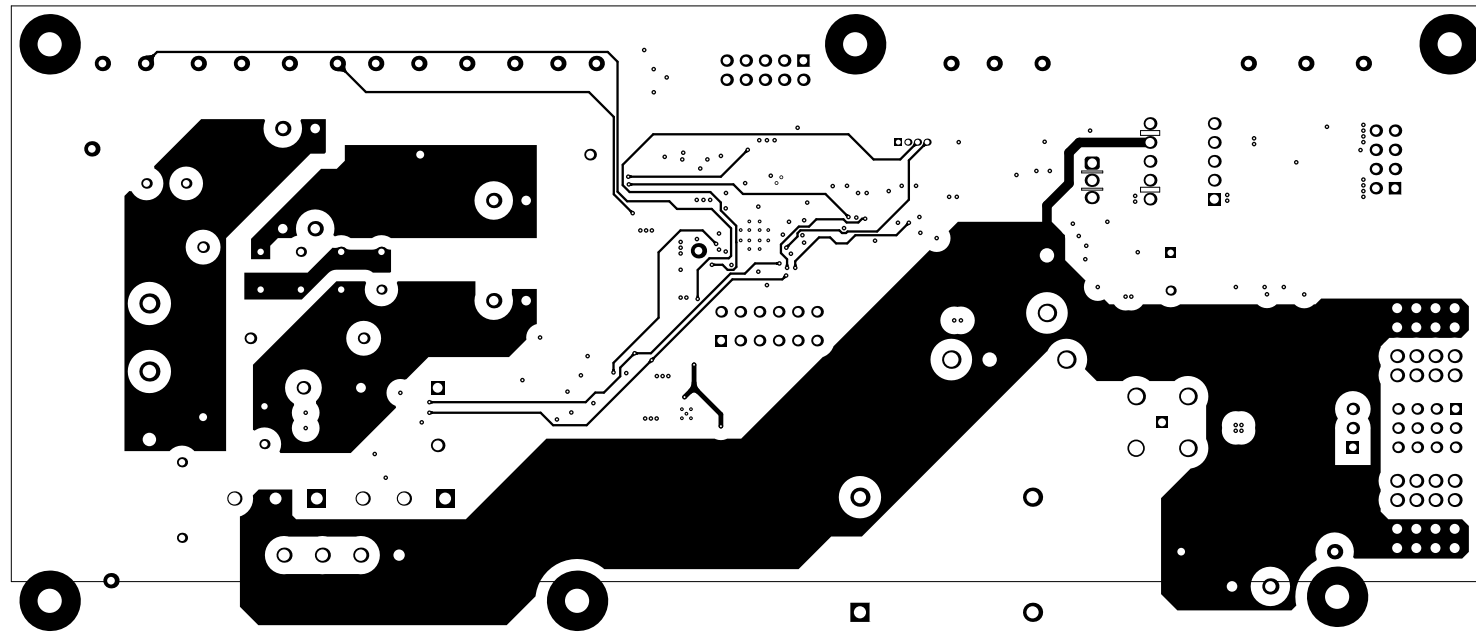
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20873	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Top Layer	GENERATED : 6/6/2017 1:50:59 PM	TEXAS INSTRUMENTS	



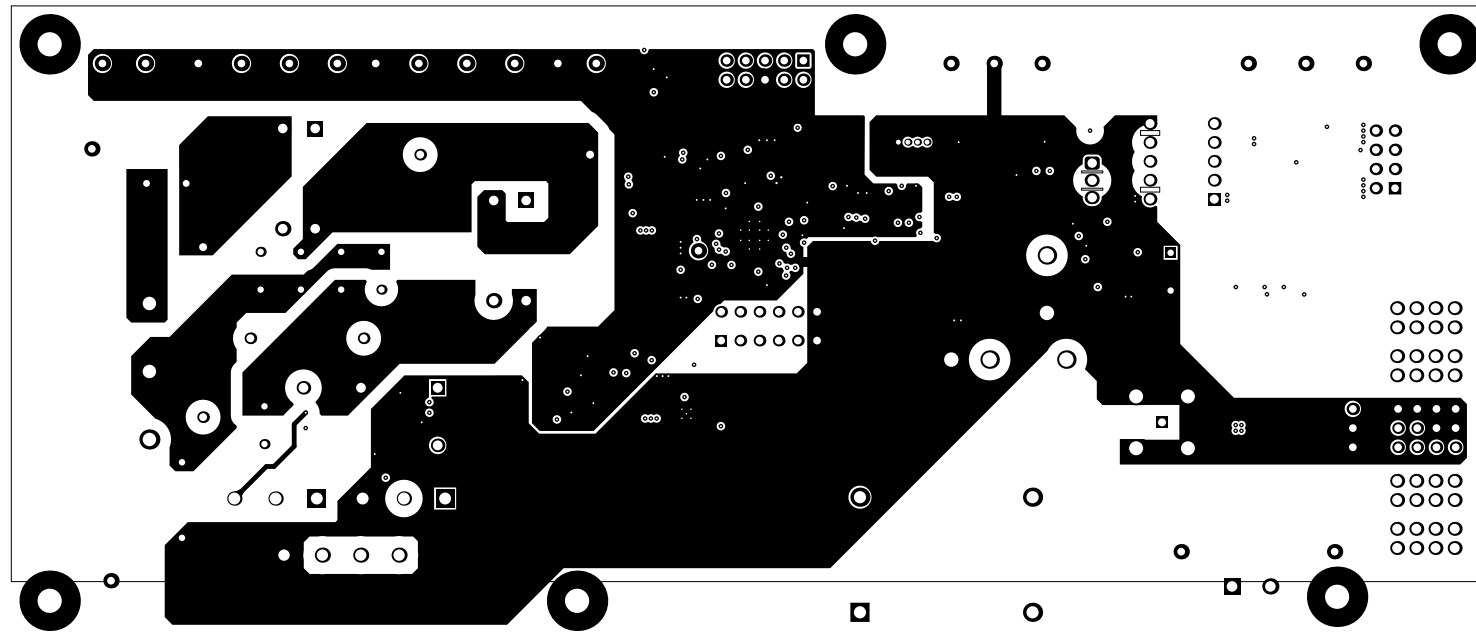
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20873	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 1	GENERATED : 6/6/2017 1:51:00 PM	TEXAS INSTRUMENTS	



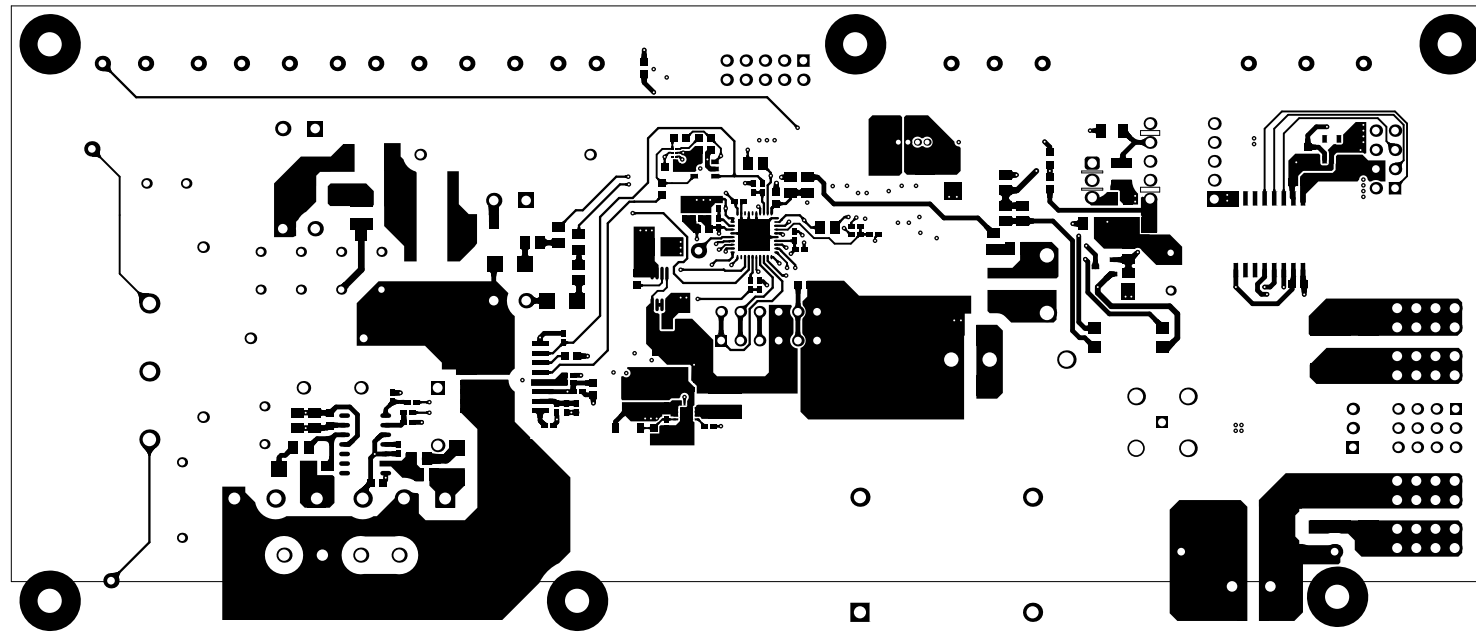
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20873	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 2	GENERATED : 6/6/2017 1:51:02 PM	TEXAS INSTRUMENTS	



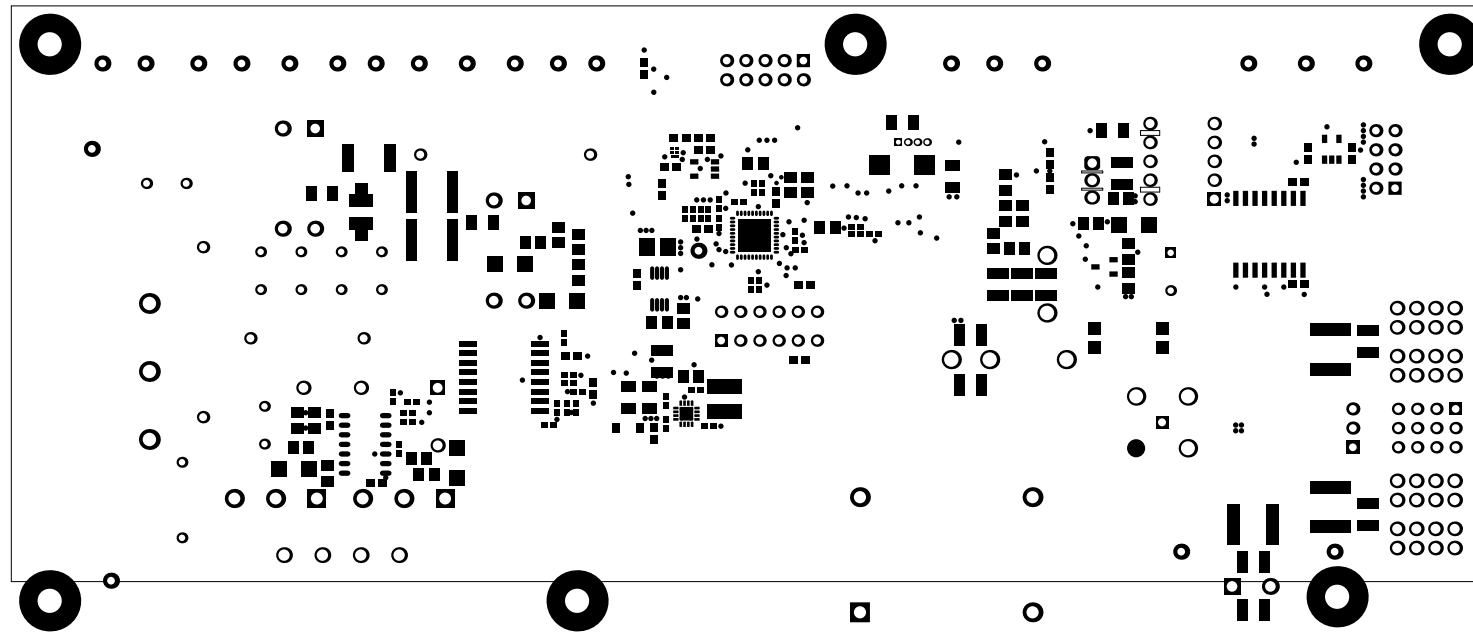
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20873	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 3	GENERATED : 6/6/2017 1:51:03 PM	TEXAS INSTRUMENTS	



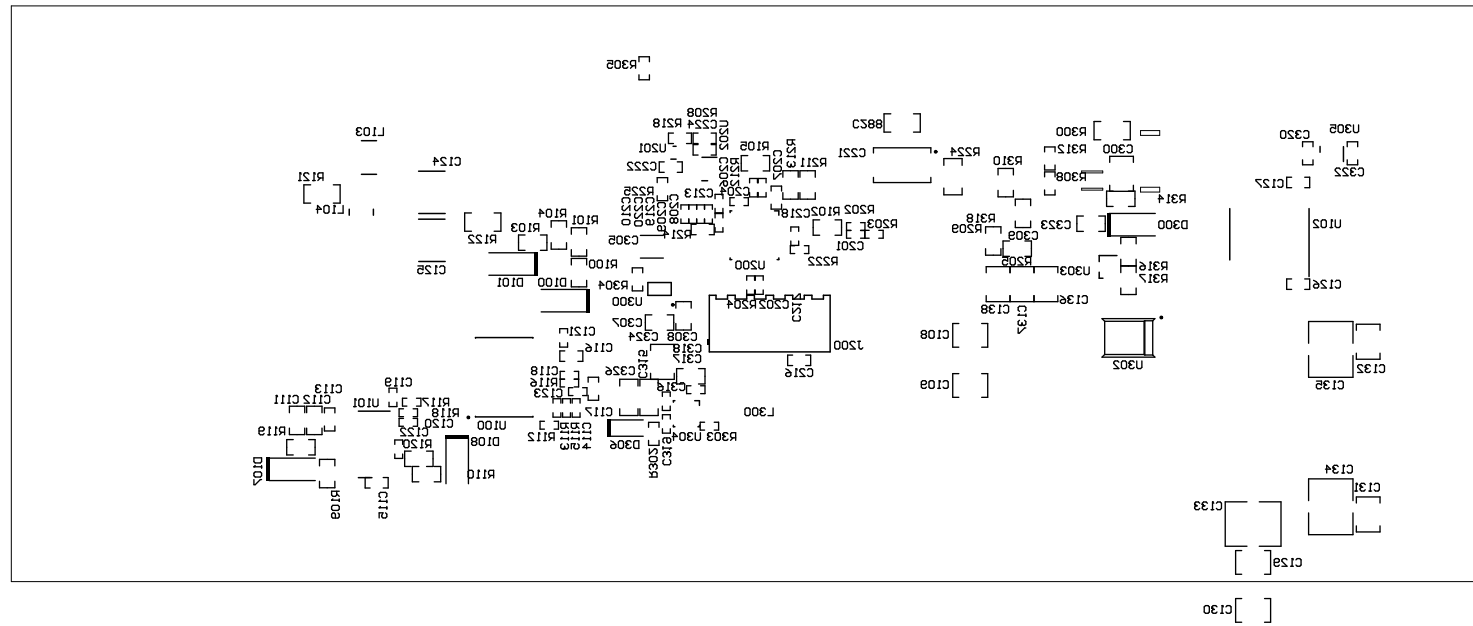
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20873	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 4	GENERATED : 6/6/2017 1:51:05 PM	TEXAS INSTRUMENTS	



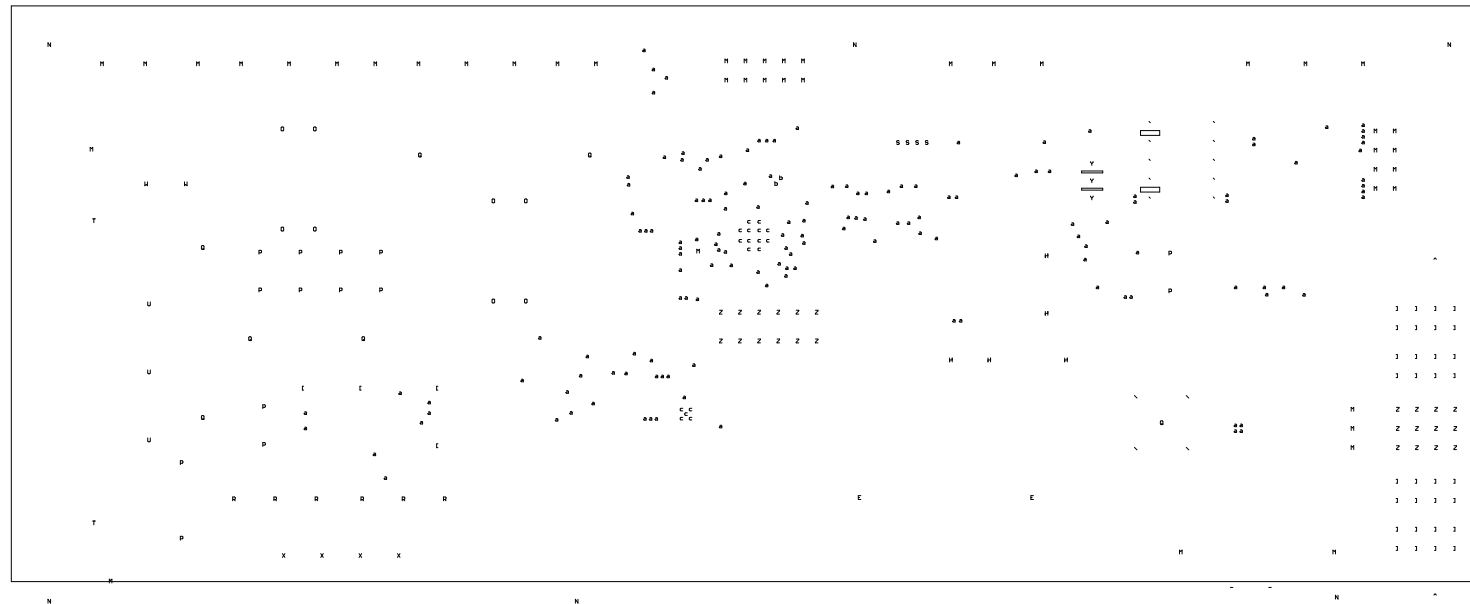
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20873	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Bottom Layer	GENERATED : 6/6/2017 1:51:06 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20873	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Bottom Solder Mask	GENERATED : 6/6/2017 1:51:08 PM	TEXAS INSTRUMENTS	

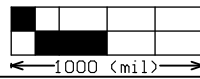


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20873	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Bottom Overlay	GENERATED : 6/6/2017	1:51:09 PM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
^	2	98.03mil (2.490mm)	NPTH	Round
T	2	137.80mil (3.500mm)	NPTH	Round
C	17	7.87mil (0.200mm)	PTH	Round
a	148	10.00mil (0.254mm)	PTH	Round
b	2	12.00mil (0.305mm)	PTH	Round
S	4	25.59mil (0.650mm)	PTH	Round
P	14	33.46mil (0.850mm)	PTH	Round
W	2	35.43mil (0.900mm)	PTH	Round
M	44	40.00mil (1.016mm)	PTH	Round
Z	24	40.16mil (1.020mm)	PTH	Round
Q	7	41.34mil (1.050mm)	PTH	Round
\	10	47.24mil (1.200mm)	PTH	Round
Y	3	49.21mil (1.250mm)	PTH	Round
O	8	50.00mil (1.270mm)	PTH	Round
[4	51.18mil (1.300mm)	PTH	Round
]	32	51.97mil (1.320mm)	PTH	Round
-	2	55.12mil (1.400mm)	PTH	Round
X	4	59.06mil (1.500mm)	PTH	Round
R	6	62.00mil (1.575mm)	PTH	Round
E	4	63.50mil (1.613mm)	PTH	Round
U	3	70.00mil (1.778mm)	PTH	Round
\	4	72.83mil (1.850mm)	PTH	Round
H	5	75.00mil (1.905mm)	PTH	Round
N	6	125.98mil (3.200mm)	PTH	Round
357 Total				

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20873	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Drill Drawing	GENERATED : 6/6/2017	1:51:11 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20873	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 6/6/2017 1:51:13 PM	TEXAS INSTRUMENTS	

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